

Infineon at a Glance

Infineon Technologies AG, Munich, Germany, offers semiconductor and system solutions for Automotive, Industrial & Multimarket sectors, for applications in communications, as well as memory products through its subsidiary Qimonda. With a global presence, Infineon operates through its subsidiaries in the USA from San Jose, California, in the Asia-Pacific region from Singapore and in Japan from Tokyo. In the 2006 financial year (ending September 30), the company achieved sales of €7.93 billion with about 41,600 employees worldwide. Infineon is listed on the Dax index of the Frankfurt Stock Exchange and on the New York Stock Exchange (ticker symbol: IFX).

SEGMENTS

Automotive, Industrial & Multimarket (AIM)

Automotive:

Engine management, security, safety, body & convenience

Industrial & Multimarket:

Chips to control electric drives and industrial facilities, energy transmission and conversion. Broad use in application areas such as household appliances, entertainment electronics, computers and communications equipment

Security & ASICs:

Security chips with contact-based or contactless interface, with and without crypto coprocessor; customized components for computer peripherals

Communication Solutions (COM)

Wireless communications:

Mobile phone platforms
Radio-frequency solutions

Wireline communications:

Access technologies for broadband

Qimonda (Memory Products)

Standard DRAMs:

For PC and notebook applications

Specialized DRAMs:

For applications in the fields of infrastructure, graphics, communications and consumer electronics, optimized for high data rates and low power consumption

Other memories:

Embedded memories, for example

APPLICATIONS

Automotive:

Power train (engine and transmission control), body & convenience, safety (airbag, ABS, EPS), infotainment

Industrial & Multimarket:

Powerpacks and power supply units for servers, PCs, notebooks, television sets, DVD players, game consoles; industrial facilities, industrial automation, medical technology, trains and building services; generation of renewable energy, e.g. wind generator; electric motor drives for washing machines, ventilators, air conditioners

Security & ASICs:

Chip-based cards in the fields of communications (SIM cards, telephone cards), payment systems, identification (ID cards, insurance cards), object identification and logistics (RFID tags); platform security for computers and networks (TPM), Hard Disk Drives (HDD), game consoles, hearing aids, computer peripherals

Wireless communications:

Mobile communications, cellular base stations
Cordless telephones
Radio-frequency technology for short, medium and long-range distances
Television receivers
Navigation

Wireline communications:

Voice communications
Broadband data communications
Integrated voice and data communications
Mobile phone infrastructure
Home networks

Data processing:

PCs, notebooks, workstations, servers

Graphic applications:

Graphic boards, game consoles

Mobile applications:

PDAs, smart phones, digital cameras, MP3 players

Consumer electronics:

Flat panel TVs, set-top boxes

1 Sources: AIM: IMS, Sept. 2006; Strategy Analytics, June 2006; COM: Gartner Dataquest, 2006; Infineon Technologies; (unless indicated otherwise, all the market data relate to the 2005 calendar year)

2 Alphabetically.

PRODUCTS	MARKET POSITION ¹	KEY CUSTOMERS ²	COMPETITORS ²
<p>Automotive: Microcontrollers (8-bit, 16-bit, 32-bit), discrete/highly integrated power semiconductors (MOSFETs, IGBTs, PROFETs), sensors (tire pressure, temperature, inertia, magnetic field sensors), components for bus systems (CAN, LIN, MOST, Flexray)</p> <p>Industrial & Multimarket: Microcontrollers (8-bit, 16-bit, 32-bit), power semiconductor ICs, discrete power semiconductors, IGBT and bipolar modules, discrete small-signal semiconductors, thyristors and diodes, sensors, radio-frequency semiconductors</p> <p>Security & ASICs: Contact-based and contactless security controllers (8-bit, 16-bit, 32-bit), security memories, RFID chips, Trusted Platform Modules (TPM), HDD controllers, memory controllers, customized chips with security functions</p>	<p>Automotive: No. 2 in automotive semiconductors (No. 1 in Europe) Leader in tire pressure monitoring systems</p> <p>Industrial & Multimarket: No. 1 in power semiconductors No. 4 for all industrial applications</p> <p>Security & ASICs: No. 1 in chip card ICs</p>	<p>Arrow, Asustek, Autoliv, Avnet Bosch Continental Delphi, Delta, Denso Emerson Gemalto, Giesecke & Devrient Hella, Hitachi Kostal Lear Microsoft Oberthur Card Systems SAC, Siemens TRW Valeo, Visteon</p>	<p>Atmel Fairchild, Freescale International Rectifier Mitsubishi National Semiconductor, NXP ON Semiconductor Renesas Samsung, STMicroelectronics Texas Instruments, Toshiba</p>
<p>Wireless communications: Baseband processors and radio-frequency transceivers for prevalent wireless communication standards (GSM, GPRS, E-GPRS, EDGE, W-CDMA, HSDPA, DECT, WDCT, Bluetooth)</p> <p>One-chip solutions or modules, in which baseband processors and radio-frequency transceivers are combined into a single component</p> <p>System solutions for mobile phones including platform design, operating software, applications; Services for system integration and customized adaptations; Analog and digital TV tuners for stationary and mobile TV receivers; Power transistors for cellular base station amplifiers for 2G through 3G, CDMA/2000 cellular standards; GPS receivers BAW filters</p> <p>Wireline communications: Interface components for voice communications in switching centers and terminal units (e.g. CODECs, SLICs, ISDN, T/E); Solutions for integrated voice and data communications; Solutions for VoIP; System solutions for wireline broadband technologies (ADSL, ADSL2, ADSL2+, VDSL, VDSL2) System solutions for DSL modems, routers, home gateways, WLAN access points</p>	<p>Wireless communications: No. 1 in radio-frequency chips No. 3 in power transistors for cellular base stations No. 4 in baseband for mobile phones (in the addressed market: digital baseband for GSM/GRPS, EDGE, UMTS) No. 4 in DECT/WDCT</p> <p>Wireline communications: No. 1 in the addressed market in access networks (DSL, T/E carriers, analog line cards, etc.)</p>	<p>Alcatel, Avnet BenQ Ericsson Huawei LG Electronics Matsushita, Motorola Nokia Samsung, Siemens ZTE</p>	<p>Agere Broadcom Conexant Ericsson Mobile Platforms Freescale NXP Qualcomm Renesas STMicroelectronics Texas Instruments</p>
<p>Standard DRAMs with memory densities from 64 Mbit to 1 Gbit</p> <p>Memory modules for PCs, notebooks, sub-notebooks, workstations and servers with memory densities from 64 MByte to 8 GByte</p> <p>Specialty memories for graphics applications (Graphics RAM)</p> <p>Specialty memories for mobile systems (Mobile-RAM, Cellular RAM)</p>	<p>No. 2 in DRAMs (first nine months 2006)</p> <p>Technological leader in 300-millimeter wafer production</p> <p>Top position in highly complex memory modules for workstations and servers</p> <p>Top position in high-performance graphics memories</p> <p>Top position in power-saving specialty memories</p>	<p>Asustek, ATI Cisco Dell EMC Fujitsu-Siemens HP, HTC IBM, Intel Kingston Lenovo, LG Electronics Microsoft, Motorola NEC, Nintendo, Nvidia Sony, Sun Microsystems</p>	<p>Elpida Hynix Micron Nanya Samsung</p>